

10/538482

JC06 Rec'd PCT/PTO 08 JUN 2005

""Express Mail" mailing label number: EV 653877445 US

Date of Deposit: June 8, 2005Case No. 9905/28
Client No. BIF023237/US**UNITED STATES PATENT AND TRADEMARK OFFICE**

| | | |
|------------------------------|---|------------------|
| In re Application of: |) | |
| |) | |
| FOURNEL et al. |) | |
| |) | |
| Serial No.: Not Yet Assigned |) | Examiner: |
| |) | Not Yet Assigned |
| |) | |
| Filing Date: Herewith |) | Group Art Unit: |
| |) | Not Yet Assigned |
| For: METHOD FOR MAKING |) | |
| A STRESSED STRUCTURE |) | |
| DESIGNED TO BE DISSOCIATED |) | |

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Dear Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and §§1.97-1.98, and more particularly in accordance with 37 C.F.R. §1.97(b), Applicants hereby cite the following references:

| No. | Date of Publication | Patentee/Applicant/Country |
|---|---------------------|----------------------------|
| 5,400,458 | 03/28/1995 | Huber et al. |
| 4,254,590 | 03/10/1981 | Eisele et al. |
| 5,374,564, | 12/20/1994 | Bruel |
| FR 2 681 472 A1 | 03/19/1993 | France |
| WO 00/48238 | 08/17/2000 | PCT |
| EP 1 050 901 A2 | 11/08/2000 | EPO |
| EP 0 410 679 A1 | 07/24/1990 | EPO |
| 101004013 | 07/05/1999 | Japan |
| Feijoo et al., "Prestressing of Bonded Wafers", Proceedings of the 1st International Symposium on Semiconductor Wafer Bonding, Science Technology and Applications, Vol. 92-7, The Electrochemical Society (1992), pp. 230-238. | | |
| Feijoo et al., "Generalized Formula for Curvature Radius and Layer Stresses Caused by Thermal Strain in Semiconductor Multilayer Structures," Appl. Phys. 54(1), 1983, page 83. | | |
| S. Timoshenko, "Analysis of Bi-Metal Thermostats," J. Opt. Soc. Am. 11 (1925), page 233-256. | | |

For the Examiner's convenience, Applicants are enclosing Form PTO-1449 (one sheet). Reference FR 2681472A1 is a French patent application. In accordance with Rule 1.98 (a)(3), the applicant states that this document discloses a multistage process for producing a thin film. The Examiner is directed to the U.S. counterpart of FR 2681472; U.S. Patent No. 5,374,564, a copy of which is included herewith.

Applicants respectfully request the Examiner's consideration of the above references and entry thereof into the record of this application.


Also enclosed is a copy of the International Search Report issued on June 3, 2004 for corresponding PCT Application No. PCT/FR03/03622 of the above-identified application.

By submitting this Statement, Applicants are attempting to fully comply with the duty of candor and good faith mandated by 37 C.F.R. §1.56. As such, this Statement is not intended to constitute an admission that any of the enclosed references, or other information referred to therein, constitutes "prior art" or is otherwise "material to patentability," as that phrase is defined in 37 C.F.R. §1.56(a).

Applicants have calculated no fee to be due in connection with the filing of this Statement. However, the Director is authorized to charge any fee deficiency associated with the filing of this Statement to a deposit account, as authorized in the Transmittal accompanying this Statement.

Respectfully submitted,

June 8, 2005


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|---|--------------------------------|--|
| FORM PTO-1449 | SERIAL NO. Not Yet Assigned | CASE NO. 107538482 9903/28 (BIF023237/US) |
| LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT | FILING DATE Herewith | GROUP ART UNIT Not Yet Assigned |
| APPLICANTS: FOURNEL et al. | | |

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | | DOCUMENT NUMBER Number-Kind Code (if known) | DATE | NAME | CLASS/ SUBCLASS | FILING DATE |
|------------------|----|--|------------|---------------|--------------------|-------------|
| | A1 | 5,400,458 | 03/28/1995 | Huber et al. | | |
| | A2 | 4,254,590 | 03/10/1981 | Eisele et al. | | |
| | A3 | 5,374,564 | 12/20/1994 | Bruel | | |

FOREIGN PATENT DOCUMENT

| EXAMINER INITIAL | | DOCUMENT NUMBER Number-Kind Code (if known) | DATE | COUNTRY | CLASS/ SUBCLAS S | TRANSLATION YES OR NO |
|------------------|----|--|------------|---------|------------------------|--------------------------|
| | A4 | FR 2 681 472 A1 | 03/19/1993 | France | | |
| | A5 | WO 00/48238 | 08/17/2000 | PCT | | |
| | A6 | EP 1 050 901 A2 | 11/08/2000 | EPO | | |
| | A7 | EP 0 410 679 A1 | 07/24/1990 | EPO | | |
| | A8 | 101004013 | 07/05/1999 | Japan | | Abstract only |

| EXAMINER INITIAL | OTHER ART – NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published. | |
|------------------|---|---|
| | A9 | Feijoo et al., "Prestressing of Bonded Wafers", Proceedings of the 1st International Symposium on Semiconductor Wafer Bonding, Science Technology and Applications, Vol. 92-7, The Electrochemical Society (1992), pp. 230-238. |
| | A10 | Feijoo et al., "Generalized Formula for Curvature Radius and Layer Stresses Caused by Thermal Strain in Semiconductor Multilayer Structures," Appl. Phys. 54(1), 1983, page 83. |
| | A11 | S. Timoshenko, "Analysis of Bi-Metal Thermostats," J. Opt. Soc. Am. 11 (1925), page 233-256. |

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|----------|-----------------|
| EXAMINER | DATE CONSIDERED |
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.